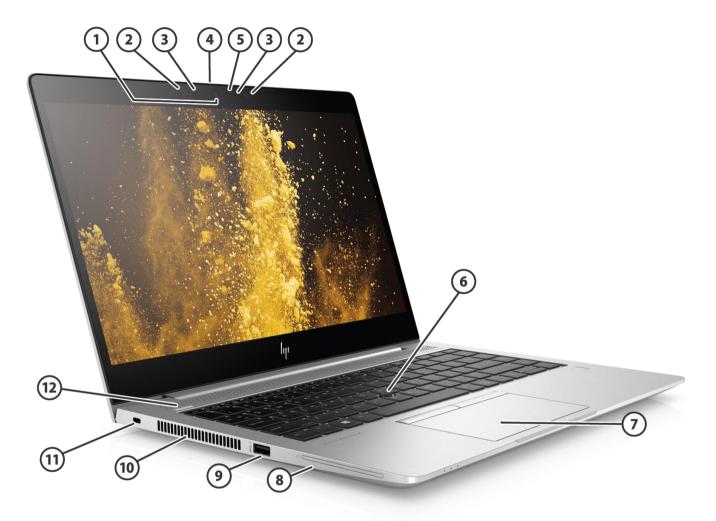
Overview

HP EliteBook 840 G6 Notebook PC



Left

- 1. HD and IR Camera (Optional)
- 2. IR Camera LEDs (Optional)
- 3. Internal Microphones
- 4. Camera Shutter
- 5. HD Camera LED
- 6. Pointstick

- 7. Glass Clickpad
- 8. Smartcard Reader (Optional)
- 9. USB 3.1 Gen 1 Charging Port
- 10. Vents
- 11. Standard Security Lock Slot (Lock sold separately)
- 12. Power Button

1. All units have a SIM card slot and icon but units that do not support WWAN are shipped with a non-removable SIM slot plug



Overview



Right

- 1. Power Connector
- 2. USB Type-C[™] with Thunderbolt[™]
- 3. Docking Connector
- 4. Ethernet Port
- 5. HDMI Port (Cable not included)

- 6. USB 3.1 Gen 1 Port
- 7. Audio Combo Jack
- 8. SIM Card Slot1
- 9. Touch Fingerprint Sensor (Optional)



Overview

AT A GLANCE

- Eye-catching Ultraslim design, premium precision-crafted machined aluminum (CNC) chassis for clean, crisp, premium look and feel
- Choice of 8th Generation Intel[®] Core[™] i5, i7 Processors
- Preinstalled with Windows 10 versions or FreeDOS
- Designed to support all HP docking options including HP's traditional Ultraslim mechanical dock and all-new Thunderbolt dock²
- Featuring HP Collaboration Keyboard with Clickpad to manage most commonly used conferencing functions with a single keystroke
- Innovative world-facing third mic improves inbound ambient noise cancellation while 360 degree mic pick-up allows everyone to clearly hear and be heard
- Optional ultrabright displays with ambient light sensor
- Choice of displays:
 - -35.6 cm (14.0") diagonal FHD IPS Anti-Glare LED-backlit, 250 nits, 45% NTSC
 - -35.6 cm (14.0") diagonal FHD IPS Anti-Glare LED-backlit non-touch 400 nits, 72% NTSC
 - -35.6cm (14.0") diagonal UHD IPS Anti-Glare LED-backlit non-touch, 400 nits, 72% NTSC
 - -35.6cm (14.0") diagonal FHD IPS Anti-Glare LED-backlit non-touch, 1000 nits, 72% NTSC with HP Sure View (Available June 2019)
 - -35.6cm (14.0") diagonal FHD IPS Anti-Glare On-Cell LED-backlit touch, 250 nits, 45% NTSC
 - -35.6 cm (14.0") diagonal FHD IPS BrightView Glass LED-backlit Corning® Gorilla® Glass 3 touch , 250 nits, 45% NTSC
 - -35.6 cm (14.0") diagonal FHD IPS Anti-Glare On-Cell LED-backlit touch, 1000 nits, 72% NTSC with HP Sure View (Available 3Q 2019)
- Optional AMD Radeon 550X discrete graphics with 2GB GDDR5 video memory
- Enterprise grade security with HP Sure Sense⁵, HP SureStart Gen5, HP Privacy Camera, HP Sure View Gen3¹, HP Sure Run Gen2, HP Sure Recover Gen2 with Embedded Reimaging², HP Sure Click, SmartCard Reader² and Touch Fingerprint reader²
- Ultimate connectivity with optional CAT16 4G/LTE WWAN, and Thunderbolt™ Docking (Dock sold separately)
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles³
- Flexible wireless connectivity options
- Choice of solid state drives up to 2 TB and DDR4 memory up to 32 GB
- Passed 19 MIL-STD 810G tests⁴
- UMA graphics: Up to 17 hours (Intel[®] 8th generation CPU and 3-cell 50 WHr battery)
- Discrete graphics: Up to 16 hours and 45 minutes (Intel® 8th generation CPU and 3-cell 50 WHr battery)

1. HP Sure View G3 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.

2.Sold separately or as an optional feature.

3. Recharges your battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

4. MIL STD 810G testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

5. HP Sure Sense requires Windows 10. See product specifications for availability.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Features

PRODUCT NAME

HP EliteBook 840 G6 Notebook PC

OPERATING SYSTEM

Preinstalled

Windows 10 Pro 64 - HP recommends Windows 10 Pro¹ Windows 10 Pro 64 (National Academic only)² Windows 10 Home 64¹ Windows 10 Home Single Language 64¹ Windows[®] 10 Enterprise 64 (Windows 10 Enterprise available with a Volume Licensing Agreement)¹ FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

PROCESSORS

Intel[®] Core[™] i7-8565U with Intel[®] UHD Graphics 620 (1.8 GHz base frequency, up to 4.6 GHz with Intel[®] Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6}

Intel[®] Core[™] i7-8665U vPro[™] processor with Intel[®] UHD Graphics 620 (1.9 GHz base frequency, up to 4.8 GHz with Intel[®] Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6}

Intel[®] Core[™] i5-8265U with Intel[®] UHD Graphics 620 (1.6 GHz base frequency, up to 3.9 GHz with Intel[®] Turbo Boost Technology, 6 MB L3 cache, 4 cores)^{3,4,5,6}

Intel[®] Core[™] i5-8365U vPro[™] processor with Intel[®] UHD Graphics 620 (1.6 GHz base frequency, up to 4.1 GHz with Intel[®] Turbo Boost Technology, 6 MB L3 cache, 4 cores)^{3,4,5,6}

Processor Family

8th Generation Intel[®] Core[™] i7 processor (i7-8665U and i7-8565U)⁶ 8th Generation Intel[®] Core[™] i5 processor (i5-8365U and i5-8265U)⁶

3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

CHIPSET

Integrated with processor



Features

GRAPHICS

Integrated

Intel[®] UHD Graphics 620⁷

Discrete

AMD Radeon[™] 550X (2 GB GDDR5 video memory)^{8,9}

Supports

Support HD decode, DX12, HDMI 1.4b¹⁰

7. HD content required to view HD images.

8. Sold separately or as an optional feature.

9. AMD Dynamic Switchable Graphics technology requires an Intel processor, plus an AMD Radeon[™] discrete graphics configuration and is not available on FreeDOS and Linux OS. With AMD Dynamic Switchable Graphics technology, full enablement of all discrete graphics video and display features may not be supported on all systems (e.g. OpenGL applications will run on the integrated GPU or the APU as the case may be). 10. HDMI cable sold separately.

DISPLAY

Non-Touch

35.6 cm (14") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC (1920 x 1080)^{7,8,11} 35.6 cm (14") diagonal FHD IPS eDP anti-glare WLED-backlit slim for HD camera, 250 nits, 45% NTSC (1920 x 1080)^{7,8,11} 35.6 cm (14") diagonal FHD IPS eDP anti-glare WLED-backlit slim for HD+IR camera, 250 nits, 45% NTSC (1920 x 1080)^{7,8,11} 35.6 cm (14") diagonal FHD IPS eDP anti- glare WLED-backlit slim for WWAN, 250 nits, 45% NTSC (1920 x 1080)^{7,8,11} 35.6 cm (14") diagonal FHD IPS eDP anti- glare WLED-backlit slim for HD camera and WWAN, 250 nits, 45% NTSC (1920 x 1080)^{7,8,11} 35.6 cm (14") diagonal FHD IPS eDP anti-glare WLED-backlit slim for HD camera and WWAN, 250 nits, 45% NTSC (1920 x 1080)^{7,8,11}

35.6 cm (14") diagonal FHD IPS eDP anti-glare WLED-backlit slim for HD+IR camera and WWAN, 250 nits, 45% NTSC (1920 x 1080)^{7,8,11}

35.6 cm (14") diagonal FHD IPS eDP + PSR anti-glare WLED-backlit slim with Ambient Light Sensor for HD+IR camera, 400 nits, 72% NTSC (1920 x 1080)^{7,8,11}

35.6 cm (14") diagonal FHD IPS eDP + PSR anti-glare WLED-backlit slim with Ambient Light Sensor for HD+IR camera and WWAN, 400 nits, 72% NTSC (1920 x 1080)^{7,8,11}

35.6 cm (14") diagonal 4K IPS eDP + PSR anti-glare WLED-backlit Ultraslim with Ambient Light Sensor for HD+IR camera and WWAN, 400 nits, 72% NTSC (3840 x 2160)^{7,8,11}

HP Sure View G3 Integrated Privacy Screen 35.6 cm (14") diagonal FHD IPS eDP + PSR anti-glare WLED-backlit flat with Ambient Light Sensor for HD+IR camera and WWAN, 1000 nits, 72% NTSC (1920 x 1080) (Available June 2019)^{7,8,11,12}

Touch

35.6 cm (14") diagonal FHD IPS eDP anti-glare On-Cell WLED-backlit slim touch screen for HD+IR camera, 250 nits, 45% NTSC (1920 x 1080)^{7,8,11}

35.6 cm (14") diagonal FHD IPS eDP anti-glare On-Cell WLED-backlit slim touch screen for HD+IR camera and WWAN, 250 nits, 45% NTSC (1920 x 1080)^{7,8,11}

35.6 cm (14") diagonal FHD IPS eDP BrightView Glass WLED-backlit slim touch screen with Corning[®] Gorilla[®] Glass 3 for HD+IR camera and WWAN, 250 nits, 45% NTSC (1920 x 1080)^{7,8,11}

HP Sure View G3 Integrated Privacy Screen 35.6 cm (14") diagonal FHD IPS eDP + PSR Anti-Glare On-Cell WLED-backlit flat with Ambient Light Sensor for HD+IR camera and WWAN, 1000 nits, 72% NTSC (1920 x 1080) (Available 3Q 2019)^{7,8,11,12}

HDMI 1.4b



Features

Supports resolution up to 4k @ 60Hz via DisplayPort[™] and @ 30Hz via HDMI¹¹

7. HD content required to view HD images.

8. Sold separately or as an optional feature.

11. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

12. HP Sure View G3 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.

Docking station model	Total number of supported displays (incl. the notebook display)	Max. resolutions supported	Dock Connectors	Technical limitations
HP UltraSlim Docking Station	3	Dual 2.5K @ 60Hz	2xDP, 1xVGA	Dual 2.5k only with both displays intoDP
HP Thunderbolt Dock G2	3	Dual 4K @ 60Hz	2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode	Dual 4k (4096 x 2160) only with: •1 DP + TB port or •USB-C alt mode + TB port Dual 4k (3840 x 2160) with any of the DP, TB or USB-C alt mode video ports
HP Elite USB-C Dock G4	3	Dual 2K @ 60Hz Single 4K @ 60Hz (3840 x 1440)	1xHDMI, 2xDP	
HP USB-C Universal Dock	3	Dual 4K @ 60Hz Single 5K @ 60Hz	2xDP	
HP USB-C Travel Dock	2	Single 2K @ 60Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time
HP USB-C Mini Dock	2	Single 4K @ 30Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time

STORAGE AND DRIVES

Primary M.2 Storage

128 GB SATA-3 SS TLC¹³ 256 GB PCIe[®] NVMe[™] Value SS TLC¹³ 256 GB PCIe[®] Gen3x4 NVMe[™] SS TLC¹³ 256 GB SATA-3 TLC Opal 2¹³



Features

512 GB PCIe[®] Gen3x4 NVMe[™] SS TLC¹³ 512 GB PCIe[®] Gen3x4 NVMe[™] SS TLC Opal 2¹³ 512 GB SATA-3 SS TLC FIPS-140-2¹³ 512 GB PCIe[®] Value¹³ 512 GB Intel[®] PCIe[®] NVMe[™] QLC + 32 GB Intel[®] Optane[™] (Memory Planned to be available Q3 2019)¹³ 1 TB PCIe[®] Gen3 x4 NVMe[™] SS TLC¹³ 2 TB PCIe[®] Gen3 x4 NVMe[™] SS TLC¹³

13. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

MEMORY

Maximum Memory

32 GB DDR4-2400 SDRAM¹⁴

Memory

32 GB DDR4-2400 SDRAM (2 X 16 GB)¹⁴ 16 GB DDR4-2400 SDRAM (1 X 16 GB)¹⁴ 16 GB DDR4-2400 SDRAM (2 X 8 GB)¹⁴ 8 GB DDR4-2400 SDRAM (1 x 8 GB)¹⁴ 8 GB DDR4-2400 SDRAM (2 x 4 GB)¹⁴ 4 GB DDR4-2400 SDRAM (1 x 4 GB)¹⁴

Memory Slots

2 SODIMM Both slots are customer accessible / upgradeable DDR4 SODIMMS, system runs at 2400 Supports Dual Channel Memory

14. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN¹⁵

Intel[®] Dual Band Wireless-AC 9560 802.11a/b/g/n/ac (2x2) Wi-Fi[®] and Bluetooth[®] 5 Combo, vPro^{™15} Intel[®] Dual Band Wireless-AC 9560 802.11a/b/g/n/ac (2x2) Wi-Fi[®] and Bluetooth[®] 5 Combo, non-vPro^{™15} Intel[®] Wi-Fi 6 AX200 802.11a/b/g/n/ac/ax (2x2) and Bluetooth[®] 5 Combo, vPro^{™16} Intel[®] Wi-Fi 6 AX200 802.11a/b/g/n/ac/ax (2x2) Bluetooth[®] 5 Combo, non-vPro^{™16}

WWAN

Intel[®] XMM[™] 7262 LTE-Advanced Cat 6¹⁷ Intel[®] XMM[™] 7360 LTE-Advanced Cat 9¹⁷ Intel[®] XMM[™] 7560 LTE-Advanced Pro Cat 16¹⁸

NFC

Near NPC300 Field Communication module

Miracast Native Miracast Support¹⁹

Ethernet



Features

Intel[®] I219-LM 10/100/1000 GbE, vPro^{™20} Intel[®] I219-V 10/100/1000 GbE, non-vPro^{™20}

15. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices. 16. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices.

 17. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.
 18. Gigabit class Category 16 4G LTE module is optional and must be configured at the factory. Module designed for up to 1 Gbps download speeds as carriers deploy 5 carrier aggregation and 100Mhz channel bandwidth, requires activation and separately purchased service contract. Backwards compatible to HSPA 3G technologies. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.
 19. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.
 20. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen Integrated 3 Multi Array Microphone 2 Integrated Stereo Speakers

Camera

720p HD camera^{7,8} 720p HD+IR camera^{7,8}

Sensors

Ambient light sensor (Select models only)

7. HD content required to view HD images.
 8. Sold separately or as an optional feature.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Collaboration Keyboard, spill resistant with drain Backlit keyboard available as an option



Features

Pointing Device

Clickpad with multi-touch gestures enabled, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

Function Keys

F1 - Display Switching F2 - Blank or Privacy F3 - Brightness Down F4 - Brightness Up F5 - Audio Mute F6 - Volume Down F7 - Volume Up F8 - Mic Mute F9 - Blank or Backlit Toggle F10 - numlk F11 - Wireless F12 - Calendar Share/Present Call Answer Call End

Hidden Function Keys

Fn+R - Break Fn+S - Sys Rq Fn+C - Scroll Lock Fn+E = Insert Fn+W = Pause

SOFTWARE AND SECURITY

Preinstalled Software

BIOS

HP BIOSphere Gen5²¹

HP Drive Lock & Automatic Drive Lock²²

BIOS Update via Network

Master Boot Record Security

Power On Authentication

Secure Erase²³

Absolute Persistence Module²⁴

Pre-boot Authentication

Software

HP Native Miracast Support²⁵ HP Connection Optimizer HP Image Assistant HP Hotkey Support HP JumpStart HP Support Assistant²⁶



Features

HP Noise Cancellation Software Buy Office (sold separately)

Manageability Features

HP Driver Packs²⁷ HP System Software Manager (SSM) HP BIOS Config Utility (BCU) HP Client Catalog HP Manageability Integration Kit Gen3²⁸ Ivanti Management Suite

Client Security Software

HP Client Security Manager Gen5²⁹ HP Fingerprint Sensor³⁰ HP Power On Authentication Windows Defender³¹

Security Management

Pre-boot Authentication TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified) SATA 0,1 port disablement (via BIOS) Serial, USB enable/disable (via BIOS) Power-on password (via BIOS) Setup password (via BIOS) Support for chassis padlocks and cable lock devices Integrated hood sensor HP Sure Click³² HP Sure Click³² HP Sure Run Gen2³⁴ HP Sure Recover Gen2³⁵

ТРМ

Model: Infineon SLB9670 Version: 7.85 Revision: TPM 2.0 FIPS 140-2 Compliant: Yes

Smartcard Reader Model number: Alcor AU9560 FIPS 201 Compliant: Yes

Features

IPv6 Certification:

Yes

MD5 Hash: Please follow the instructions below to access MD5 Hash.

Log-on to http://hp.com/support, enter your product name, select software and drivers, select OS, select driver. After selecting the driver, click on "Associated files" and then click on "Download". When opening the file, under "Purpose" you should see the appropriate "SOFTPAQ MD5:" Field

Graphics (Intel Video Driver): TBD WWAN: TBD WLAN: TBD

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?:

UEFI version: 2.6

21. HP BIOSphere Gen5 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations

22. HP Drive Lock & Automatic Drive Lock is not supported on NVMe drives

23. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel[®] Optane[™].

24. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

25. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.

25. HP Support Assistant requires Windows and Internet access.

27. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.

28. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.

29. HP Client Security Manager Gen5 requires Windows and is available on the select HP Pro and Elite PCs. See product specifications for details.

30. HP Fingerprint Sensor sold separately or as an optional feature.

31. Windows Defender Opt in and internet connection required for updates.

32. HP Sure Click is available on select HP platforms and supports Microsoft Internet Explorer, Google Chrome™, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.

33. HP Sure Start Gen5 is available on select HP PCs with Intel processors. See product specifications for availability.

34. HP Sure Run Gen2: See product specifications for availability.

35. HP Sure Recover Gen2: See product specifications for availability. Requires an open, wired network connection. Not available on platforms with multiple internal storage drives. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover (Gen1) does not support platforms with Intel[®] Optane[™]. 36. HP Sure Sense requires Windows 10. See product specifications for availability.



Features

POWER

Power Supply

HP Smart 45 W External AC power adapter³⁶ HP Smart 45 W External AC power adapter, 2-prong (Japan only)³⁶ HP Smart 65 W External AC power adapter³⁶ HP Smart 65 W EM External AC power adapter³⁶ 45 W USB Type-C[™] adapter³⁶ 65 W USB Type-C[™] adapter³⁶

Primary Battery

HP Long Life 3-cell, 50 Wh Li-ion³⁷ Support HP Fast Charge (Up to 50% in 30 minutes with 65W AC Adapter)³⁸

Battery Life

UMA graphics: Up to 17 hours and 15 minutes (Intel® 8th generation CPU and 3-cell 50 WHr battery)³⁹

Power Cord

2-wire plug - 1.0 m (Japan only)³⁶ 3-wire plug - 1.0 m³⁶ 3-wire plug - 1.8 m³⁶ Duckhead power cord - 1.0 m³⁶ Duckhead power cord - 1.8 m³⁶

36. Availability may vary by country.

37. Battery is internal and not replaceable by customer. Serviceable by warranty.

38. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

39. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Non-Touch

Starting at 3.27 lbs (non-touch); Starting at 3.32 lb (touch)⁴⁰ Starting at 1.48 kg (non-touch); Starting at 1.51 kg (touch)⁴⁰

Touch

Starting at 3.32 lbs⁴⁰ Starting at 1.51 kgs⁴⁰

Dimensions (w x d x h)

Non-touch 12.84 x 9.22 x 0.71 in 32.6 x 23.43 x 1.79 cm

Touch

12.84 x 9.22 x 0.71 in 32.6 x 23.43 x 1.805 cm

40. Weight will vary by configuration.



Features

PORTS/SLOTS

Ports

1 Thunderbolt[™] (USB Type-C[™] connector)
2 USB 3.1 Gen 1 (1 charging)
1 docking connector
1 HDMI 1.4¹⁰
1 RJ-45
1 AC power
1 Headphone/microphone combo jack
1 SIM card slot
1 Smartcard reader
Standard Security Lock Slot (Lock sold separately)

10. HDMI cable sold separately.

SERVICE AND SUPPORT

HP Services offers 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to http://www.hp.com/support/batterywarranty for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.41

41. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



ENVIRONMENTAL & INDUSTRY

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration 				
	•US ENERGY STAR®				
	• EPEAT [®] Gold registered in the Ur your country. TCO	• EPEAT [®] Gold registered in the United States. See http://www.epeat.net for registration status in your country. TCO			
System Configuration	The configuration used for the En Notebook model is based on a "Typ		Noise Emissions data for the		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz		
Normal Operation (Short idle)	6.97 W	6.98 W	7.02 W		
Normal Operation (Long idle)	4.09 W	3.86 W	4.07 W		
Sleep	1.28 W	1 W	1.31 W		
Off	0.40 W	0.40 W	0.41 W		
	Energy efficiency data listed is for a family. HP computers marked with Environmental Protection Agency family does not offer ENERGY STAR for a typically configured PC feat Microsoft Windows® operating syst	the ENERGY STAR® Logo are com (EPA) ENERGY STAR® specification (© compliant configurations, then uring a hard disk drive, a high e	npliant with the applicable U.S. ons for computers. If a model energy efficiency data listed is		
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz		
Normal Operation (Short idle)	24 BTU/hr	24 BTU/hr	24 BTU/hr		
Normal Operation (Long idle)	14 BTU/hr	13 BTU/hr	14 BTU/hr		
Sleep	4 BTU/hr	3 BTU/hr	4 BTU/hr		
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr		
	Heat dissipation is calculated based for one hour.	d on the measured watts, assumi	ng the service level is attained		



Declared Noise		Sound Power	Sc	ound Pressure
Emissions	(LwAd, bels)			pAm, decibels)
(in accordance with			(-	
ISO 7779 and ISO 9296)				
130 / / / 3 and 130 3230)				
Typically Configured –		2.5		13.8
Idle				
Fixed Disk – Random		2.5		15.3
writes				
Longevity and Upgrading	This product	can be upgraded, possibly extending	r its usoful life by sove	ral voare Upgradoablo
Longevity and opgrading		l/or components contained in the pro		
	• 3 USB ports		Judet may metade.	
	• 1 PC card s			
	• 1 ExpressC			
	• 1 IEEE 1394			
		memory slots		
		pansion base docking station		
	 T multi-bay Interchange 	y II storage port		
	• Interchange			
	Spare parts a	are available throughout the warrant	ty period and or for up	to "5" vears after the end of
	production.		, , , , , , , , , , , , , , , , , , ,	,
Batteries	This battery	(s) in this product comply with EU Dir	ective 2006/66/EC	
	Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell)			
	Battery type: lithium/manganese dioxide			
Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive -			
	2011/65/EC.			
		oduct is designed to comply with the	Waste Electrical and E	ectronic Equipment (WEEE)
	 Directive – 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking 			
		oxic Enforcement Act of 1986).		autornia, Sare Drinking
		ct is in compliance with the IEEE 1680	0 (EPEAT) standard at t	he Gold level, see
	http://www.			
		rts weighing over 25 grams used in tl	he product are marked	per IS011469 and IS01043.
		ct contains 3% post-consumer recycl		
		ct is 94.5% recycle-able when proper	rly disposed of at end o	
Packaging Materials	External:	PAPER/Corrugated		261 g
	Internal:	PLASTIC/Polyethylene Expanded -	- EPE	68 g
		PLASTIC/Polyethylene low density	y	14 g
		PLASTIC/Polypropylene - PP		4 g
Material II	This is the			after all to the fort
Material Usage		does not contain any of the followin		s of regulatory limits (refer
	to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos			F)•
				7.
	Certain Azo) Colorants		



	Cadmium Chloringted Hydrocorbons
	Chlorinated Hydrocarbons Chlorinated Paraffins
	• Formaldehyde
	Halogenated Diphenyl Methanes
	Lead carbonates and sulfates
	Lead and Lead compounds
	Mercuric Oxide Batteries
	 Nickel – finishes must not be used on the external surface designed to be frequently handled or
	carried by the user.
	Ozone Depleting Substances
	Polybrominated Biphenyls (PBBs)
	Polybrominated Biphenyl Ethers (PBBEs)
	Polybrominated Biphenyl Oxides (PBBOs)
	Polychlorinated Biphenyl (PCB)
	Polychlorinated Terphenyls (PCT)
	 Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been
	voluntarily removed from most applications.
	Radioactive Substances
	• Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	
i ackaging obage	HP follows these guidelines to decrease the environmental impact of product packaging:
	• Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging
	materials.
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	 Design packaging materials for ease of disassembly.
	• Maximize the use of post-consumer recycled content materials in packaging materials.
	• Use readily recyclable packaging materials such as paper and corrugated materials.
	Reduce size and weight of packages to improve transportation fuel efficiency.
	 Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
	Trastic packaging matchats are marked according to 150 T1405 and Div 0120 standards.
End-of-life Management	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To
-	
and Recycling	recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP
	sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible
	manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for
	each product type for use by treatment facilities. This information (product disassembly
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers.
	These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM
	customers who integrate and re-sell HP equipment.
HP Inc. Corporate	For more information about HP's commitment to the environment:
Environmental	
Information	
	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
1	
	Eco-label certifications



Technical Specifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
ISO 14001 certificates:
http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K _Certificate.pdf
and
http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	19V
	Average Operating Power	Win 10
	Integrated Graphics	6.78W
	Discrete Graphics	13 W
	Max Operating Power	Discrete < 65W UMA < 45W
Temperature	Operating	32° to 95° F (0° to 35° C)
	Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	Operating	10% to 90%, non-condensing
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature
Shock	Operating	40 G, 2 ms, half-sine
	Non-operating	200 G, 2 ms, half-sine
Random Vibration	Operating	0.75 grms
	Non-operating	1.50 grms
Altitude (unpressurized)	Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
	Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)
Planned Industry Standard	UL	Yes
Certifications	CSA	Yes
	FCC Compliance	Yes
	ENERGY STAR [®]	Select models ⁴²
	EPEAT®	Registered Silver in United States ⁴³
	ICES	Yes
	Australia / NZ A-Tick Compliance	Yes
	CCC	Yes
	Japan VCCI Compliance	Yes
	КС	Yes
	BSMI	Yes
	CE Marking Compliance	Yes
	BNCI or BELUS	Yes
	CIT	Yes



GOST	Yes
Saudi Arabian Compliance	Yes
(ICCP)	
SABS	Yes

42. Configurations of the HP Elitebook 840 G6 that are ENERGY STAR[®] qualified are identified as HP Elitebook 840 G6 ENERGY STAR on HP websites and on http://www.energystar.gov.

43. EPEAT[®] registered where applicable. EPEAT registration varies by country. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options.



DISPLAYS

NOTE: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Panel LCD 14 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 45 percent cg 250 nits eDP	Outline Dimensions (W x H)	316.17 x 197.98 mm (max)
	Active Area	309.37 x 174.02 mm (typ.)
slim	Weight	285 g (max)
	Diagonal Size	14.0 inch
	Thickness	3.0 mm (max)
	Interface	eDP 1.2 (2 lane)
	Surface Treatment	Anti-Glare
	Touch Enabled	No
	Contrast Ratio	600:1 (typ.)
	Refresh Rate	60 Hz
	Brightness	250 nits
	Pixel Resolution	1920 x 1080 (FHD)
	Format	NTSC
	Backlight	LED
	Color Gamut Coverage	45%
	Color Depth	6 bits
	Viewing Angle	UWVA 85/85/85/85



Panel LCD 14 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 45 percent cg 250 nits eDP	Outline Dimensions (W x H)	316.112 x 197.98 mm (max)
	Active Area	309.37 x 174.02 mm (typ.)
slim BrightView Touch	Weight	425 g (max)
	Diagonal Size	14.0 inch
	Thickness	3.8 mm (panel side w/ glass) / 4 mm (PCBA side) (max)
	Interface	eDP 1.2
	Surface Treatment	BrightView Glass
	Touch Enabled	Yes
	Contrast Ratio	600:1 (typ.)
	Refresh Rate	60 Hz
	Brightness	250 nits
	Pixel Resolution	1920 x 1080 (FHD)
	Format	NTSC
	Backlight	LED
	Color Gamut Coverage	45%
	Color Depth	6 bits
	Viewing Angle	UWVA 85/85/85/85

Panel LCD 14 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 45 percent cg 250 nits eDP	Outline Dimensions (W x H)	316.112 x 197.98 mm (max)
	Active Area	309.37 x 174.02 mm (typ.)
slim On-cell touch	Weight	290 g (max)
	Diagonal Size	14.0 inch
	Thickness	3.0 mm (panel side) / 3.2 mm (PCBA Side) (max)
	Interface	eDP 1.2
	Surface Treatment	Anti-Glare On-cell
	Touch Enabled	Yes
	Contrast Ratio	600:1 (typ.)
	Refresh Rate	60 Hz
	Brightness	250 nits
	Pixel Resolution	1920 x 1080 (FHD)
	Format	NTSC
	Backlight	LED
	Color Gamut Coverage	45%
	Color Depth	6 bits
	Viewing Angle	UWVA 85/85/85/85

Technical Specifications

Panel LCD 14 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 72 percent cg 400 nits eDP 1.3+PSR slim

Outline Dimensions (W x H)	316.11 x 197.98 mm (max)
Active Area	309.31 x 173.99 mm
Weight	<285 g (max)
Diagonal Size	14.0 inch
Thickness	3.0 mm (max)
Interface	eDP 1.3 + PSR (2 lane)
Surface Treatment	Anti-Glare
Touch Enabled	No
Contrast Ratio	600:1 (typ.)
Refresh Rate	60 Hz
Brightness	400 nits
Pixel Resolution	1920 x 1080 (FHD)
Format	NTSC
Backlight	LED
Color Gamut Coverage	72%
Color Depth	6 bits + Hi FRC
Viewing Angle	UWVA 85/85/85/85



Technical Specifications

Panel LCD 14 inch diagonal UHD Outline Dimensions (W x H) 315.31 x 199.54 mm (max) (w/ PCB) (3840 x 2160) Anti-Glare WLED

(3840 x 2160) Anti-Glare WLED UWVA 72 percent cg 400 nits eDP		
	Active Area	309.31 x 173.99 mm
1.3 + PSR Ultraslim	Weight	<240 g (max)
	Diagonal Size	14.0 inch
	Thickness	2.4 mm (max)
	Interface	eDP 1.3 + PSR (4 lane)
	Surface Treatment	Anti-Glare
	Touch Enabled	No
	Contrast Ratio	1200:1 (typ.)
	Refresh Rate	60 Hz
	Brightness	400 nits (typ.)
	Pixel Resolution	3840 x 2160 (UHD)
	Format	NTSC
	Backlight	LED
	Color Gamut Coverage	72%
	Color Depth	8 bits
	Viewing Angle	UWVA 85/85/85/85

Panel LCD 14 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 72 percent cg 1000 nits eDP 1.4+PSR2 flat

	515.51 × 155.450 mm (max)
Active Area	309.312 x 173.988 mm (typ.)
Weight	265 g (max)
Diagonal Size	14.0 inch
Thickness	3.0 mm (max)
Interface	eDP 1.4 + PSR2 (4 lane)
Surface Treatment	Anti-Glare
Touch Enabled	No
Contrast Ratio	2000:1 (typ.)
Refresh Rate	60 Hz
Brightness	1000 nits
Pixel Resolution	1920 x 1080 (FHD)
Format	RGB

Outline Dimensions (W x H) 315.31 x 195.498 mm (max)



Backlight	LED
Color Gamut Coverage	72%
Color Depth	8 bits
Viewing Angle	UWVA 85/85/85/85

Panel LCD 14 inch diagonal FHD
(1920 x 1080) Anti-Glare WLED
UWVA 72 percent cg 1000 nits
eDP 1.4+PSR flat On-cell touch
Privacy

Outline Dimensions (W x H)	315.31 x 197.138 mm (max)
Active Area	309.312 x 173.988 mm (typ.)
Weight	270 g (max)
Diagonal Size	14.0 inch
Thickness	3.2 mm (max)
Interface	eDP 1.4 + PSR2 (4 lane)
Surface Treatment	Anti-Glare On-cell
Touch Enabled	YES
Contrast Ratio	2000:1 (typ.)
Refresh Rate	60 Hz
Brightness	1000 nits
Pixel Resolution	1920 x 1080 (FHD)
Format	RGB
Backlight	LED
Color Gamut Coverage	72%
Color Depth	8 bits
Viewing Angle	UWVA 85/85/85/85



STORAGE¹

SSD 128 GB 2280 M2	Form Factor	M.2 2280
SATA-3 TLC	Capacity	128 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	ATA-8, SATA 3.0
	Maximum Sequential Read	Around 540 ~ 560 MB/s
	Maximum Sequential Write	Around 380 ~ 530 MB/s
	Logical Blocks	250,069,680
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; DIPM; TRIM; DEVSLP

SSD 1 TB 2280 PCIe-3x4 NVMe	Form Factor	M.2 2280	
1	Three Layer Cell single-sided	Capacity	1 TB
		NAND Type	TLC
		Height	0.09 in (2.3 mm)
		Width	0.87 in (22 mm)
		Weight	0.02 lb (10 g)
		Interface	PCIe NVMe Gen3X4
		Maximum Sequential Read	Around 3200 ~ 3480 MB/s
	Maximum Sequential Write	e Around 2400 ~ 3037 MB/s	
	Logical Blocks	2,000,409,264	
		Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
		Features	ATA Security; TRIM; L1.2
-			
S	SD 256 GB 2280 M2	Form Factor	M.2 2280
F	PCIe-3x4 SS NVMe TLC	Capacity	256 GB
		NAND Type	TLC

0.09 in (2.3 mm)

0.87 in (22 mm)

0.02 lb (10 g)

Height

Width

Weight



	Maximum Sequential Write	e Around 1300 ~ 1663 MB/s	
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security; TRIM; L1.2	
SSD 256 GB 2280 M2 SATA-3 Self	Form Factor	M.2 2280	
Encrypted OPAL2 Three Layer	Capacity	256 GB	
Cell	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (10 g)	
	Interface	ATA-8, SATA 3.0	
	Maximum Sequential Read	Around 530 ~ 560 MB/s	
	Maximum Sequential Write	Around 500 ~ 530 MB/s	
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security; TCG OPAL 2.0; DIPM; TRIM; DEVSLP	
Value	Capacity NAND Type Height Width Weight Interface Maximum Sequential Read Maximum Sequential Write Logical Blocks Operating Temperature Features		
2 TB 2280 PCIe-3x4 NVMe Three Layer Cell single-sided	Form Factor Capacity NAND Type Height Width Weight	M.2 2280 2 TB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) 0.02 lb (10 g)	
	-06200102 DA16444 World		Dago

•		
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Around 2900 ~ 3000 MB/s
	Maximum Sequential Write	Around to 2100 MB/s
	Logical Blocks	3,907,029,168
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2
SSD 512 GB 2280 M2 PCIe-3x4 SS	Form Factor	M.2 2280
NVMe TLC	Capacity	512 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Around 2700 ~ 3400 MB/s
	Maximum Sequential Write	Around 1390 ~ 2956 MB/s
	Logical Blocks	1,000,215,215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2
SSD 512 GB 2280 M2 SATA-3	Form Factor	M.2 2280
Three Layer Cell Federal Information Processing	Capacity	512 GB
Standard	NAND Type	TLC
	Height	2.6 mm Max
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	ACS-3, SATA 3.2
	Maximum Sequential Read	Around 530 MB/s
	Maximum Sequential Write	Around 400 MB/s
	Logical Blocks	1,000,215,216
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TCG Opal 2.0; FIPS; DIPM; TRIM; DEVSLP
SSD 512 GB 2280 PCIe NVMe	Form Factor	M.2 2280
Value	Capacity	512 GB
	NAND Type	TLC/QLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)



Weight	0.02 lb (10 g)
Interface	PCIe NVMe Gen3X4
Maximum Sequential Read	Around 1500 ~ 1700 MB/s
Maximum Sequential Write	Around 860 ~ 1500 MB/s
Logical Blocks	1,000,215,215
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security; TRIM; L1.2



Technical Specifications

SSD 512 GB 2280 PCIe-3x4 NVMe	Form Factor	M.2 2280
Self Encrypted OPAL2 Three	Capacity	512 GB
Layer Cell	NAND Type	TLC
	Height	2.6 mm Max
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Around 2900 ~ 3400 MB/s
	Maximum Sequential Write	Around 1000 ~ 2500 MB/s
	Logical Blocks	1,000,215,216
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TCG Opal 2.0; FIPS; DIPM; TRIM; DEVSLP

1. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

NETWORKING/COMMUNICATIONS

Intel® 9560 802.11a/b/g/n/ac (2 x 2) WiFi® and Bluetooth® 5.0 Combo vPro ¹		IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac
	Interoperability	Wi-Fi [®] certified
	Frequency Band	•802.11b/g/n 2.402 – 2.482 GHz •802.11a/n 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	 •802.11b: 1, 2, 5.5, 11 Mbps •802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) •802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security ³	•IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only •AES-CCMP: 128 bit in hardware



Technical Specifications

Network Architecture	 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI Ad-hoc (Peer to Peer) 	
Models	Infrastructure (Access P	•
Roaming		oaming between access points
Output Power ²	 802.11b: +18.5dBm minimum 802.11g: +17.5dBm minimum 802.11a: +18.5dBm minimum 802.11n HT20(2.4GHz): +15.5dBm minimum 802.11n HT40(2.4GHz): +14.5dBm minimum 802.11n HT20(5GHz): +15.5dBm minimum 802.11n HT40(5GHz): +14.5dBm minimum 802.11ac VHT80(5GHz): +11.5dBm minimum 802.11ac VHT160(5GHz): +11.5dBm minimum 	
Power Consumption	 Transmit mode 2.0 W Receive mode 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated) Connected Standby 10 mW Radio disabled 8 mW 	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure	
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm	
Weight	Туре 2230: 2.8 g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating10% to 90% (non-condensing)Non-operating5% to 95% (non-condensing)	



	Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
	LED Activity	LED Amber – Radio OFF LED OFF – Radio ON	
HP Integrated Module wit	h Bluetooth 4.0/4.1/4.2/5	.0 Wireless Technology	
	Bluetooth Specification	 4.0/4.1/4.2/5.0 Compliant 2402 to 2480 MHz Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH) Legacy: 3 Mbps signaling data rate¹ 2.17 Mbps BLE: 1 Mbps signaling data rate¹ 0.2 Mbps 1. Actual throughput may vary. 	
	Frequency Band		
	Number of Available Channels		
	Signaling Data Rate		
		Legacy: Synchronous Cor channels	nnection Oriented links up to 3, 64 kbps, voice
			onnection Less links 2178.1 kbps/177.1 kbps 64 kbps symmetric (3-EV5)
	Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device w a maximum transmit power of + 4 dBm for BR and EDR.	
	Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW	V
	Bluetooth Software Supported	Microsoft Windows Bluet	ooth Software
	Power Management	Microsoft Windows ACPI,	and USB Bus Support
	Certifications	FCC (47 CFR) Part 15C, Se	ction 15.247 & 15.249
	Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark	
	Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Complia LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directe LE L2CAP Connection Orie Train Nudging & Interlace BT4.2 ESR08 Compliance LE Secure Connection- Ba LE Privacy 1.2 –Link Laye LE Privacy 1.2 –Extended LE Data Packet Length Ex FAX Profile (FAX) Basic Imaging Profile (BIF Headset Profile (HSP)	ed Advertising ented Channels ed Scan asic/Full r Privacy I Scanner Filter Policies ctension



Technical Specifications

Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Security & Manageability Intel[®] vPro[™] support with appropriate Intel[®] chipset components

Wireless access point and Internet service is required. Availability of public wireless access point is limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices
 The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



Intel® 9560 802.11a/b/g/n/ac (2 x 2) WiFi® and Bluetooth® 5.0 Combo non-vPro ¹	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac
	Interoperability	Wi-Fi [®] certified
	Frequency Band	•802.11b/g/n 2.402 – 2.482 GHz •802.11a/n 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	 •802.11b: 1, 2, 5.5, 11 Mbps •802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) •802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security ³	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI
	Network Architecture	Ad-hoc (Peer to Peer)
	Models	Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power ²	 802.11b: +18.5dBm minimum 802.11g: +17.5dBm minimum 802.11a: +18.5dBm minimum 802.11n HT20(2.4GHz): +15.5dBm minimum 802.11n HT40(2.4GHz): +14.5dBm minimum 802.11n HT20(5GHz): +15.5dBm minimum 802.11n HT40(5GHz): +14.5dBm minimum 802.11ac VHT80(5GHz): +11.5dBm minimum 802.11ac VHT160(5GHz): +11.5dBm minimum
	Power Consumption	 Transmit mode 2.0 W Receive mode 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated) Connected Standby 10 mW Radio disabled 8 mW



Technical Specifications

Power Management	ACPI and PCI Express con 802.11 compliant power	npliant power management saving mode
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure	
		d 2.4/5 GHz antennas are provided to the card to munications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm	
Weight	Туре 2230: 2.8 д	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF LED OFF – Radio ON	

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.



Technical Specifications

Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Wireless access point and Internet service is required. Availability of public wireless access point is limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices
 The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Intel® Wi-Fi® 6 AX200 +	Wireless LAN Standards	IEEE 802.11a
BT5 vPro ¹		IEEE 802.11b
		IEEE 802.11g
		IEEE 802.11n
		IEEE 802.11ac
		IEEE 802.11ax
		IEEE 802.11d
		IEEE 802.11e
		IEEE 802.11h



	IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
Interoperability	Wi-Fi [®] certified
Frequency Band	•802.11b/g/n/ax 2.402 – 2.482 GHz •802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
Data Rates	 •802.11b: 1, 2, 5.5, 11 Mbps •802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) •802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) •802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM
Security ³	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ²	 802.11b: +18.5dBm minimum 802.11g: +17.5dBm minimum 802.11a: +18.5dBm minimum 802.11n HT20(2.4GHz): +15.5dBm minimum 802.11n HT40(2.4GHz): +14.5dBm minimum 802.11n HT20(5GHz): +15.5dBm minimum 802.11n HT40(5GHz): +14.5dBm minimum 802.11ac VHT80(5GHz): +11.5dBm minimum 802.11ac VHT160(5GHz): +10dBm minimum 802.11ax VHT160(5GHz): +10dBm minimum
Power Consumption	•Transmit mode 2.0 W •Receive mode 1.6 W •Idle mode (PSP) 180 mW (WLAN Associated)



Technical Specifications

	•Idle mode 50 mW (WLA •Connected Standby 10r •Radio disabled 8 mW	-
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity ³	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ax, MCS11(HT40): -59dBm maximum 802.11ax, MCS11(VHT160): -58.5dBm maximum	
Antenna type	enclosure Two embedded dual bar	with spatial diversity, mounted in the display ad 2.4/5 GHz antennas are provided to the card to nmunications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	1. Туре 2230: 2.3 x 22.0 2. Туре 1216: 1.67 x 12.	
Weight	1. Type 2230: 2.8g 2. Type 126: 1.3g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

	1. Actual throughput may vary.
	BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps
Channels	BLE: 0~39 (2 MHz/CH)
Number of Available	Legacy: 0~79 (1 MHz/CH)
Frequency Band	2402 to 2480 MHz
Bluetooth Specification	4.0/4.1/4.2/5.0/5.1 Compliant

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels



Technical Specifications

	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.		
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW		
Bluetooth Software Supported	Microsoft Windows Bluetooth Software		
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark		
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)		
Security & Manageability	Intel® vPro [™] support with appropriate Intel® chipset components		

Security & Manageability Intel® vPro™ support with appropriate Intel® chipset components

Wireless access point and Internet service is required. Availability of public wireless access point is limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices
 The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
 Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



Intal Wi Ei® 6 AV200 +	Wireless LAN Standards	
Intel Wi-Fi® 6 AX200 + BT5 non-vPro ¹	wireless LAN Standards	IEEE 802.11a
		IEEE 802.11b
		IEEE 802.11g
		IEEE 802.11n
		IEEE 802.11ac
		IEEE 802.11ax
		IEEE 802.11d
		IEEE 802.11e
		IEEE 802.11h
		IEEE 802.11i
		IEEE 802.11k
		IEEE 802.11r
		IEEE 802.11v
	Interoperability	Wi-Fi [®] certified
	Frequency Band	•802.11b/g/n/ax
		2.402 – 2.482 GHz
		•802.11a/n/ac/ax
		4.9 – 4.95 GHz (Japan)
		5.15 – 5.25 GHz
		5.25 – 5.35 GHz
		5.47 – 5.725 GHz
		5.825 – 5.850 GHz
	Data Rates	•802.11b: 1, 2, 5.5, 11 Mbps
	Dala Kales	•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		•802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		•802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
		•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &
		160MHz)
		• 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz &
		• 602.118X. MC50 ~ MC511, (155 and 255) (20MH2, 40MH2, 60MH2 & 160MHz)
		-
	Modulation	Direct Sequence Spread Spectrum
		OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM
	Security ³	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
		•AES-CCMP: 128 bit in hardware
		•802.1x authentication
		•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. •WPA2 certification
		•IEEE 802.11i
		•Cisco Certified Extensions, all versions through CCX4 and CCX Lite
		•WAPI
	Network Architecture	Ad-hoc (Peer to Peer)
	Models	Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power ²	• 802.11b: +18.5dBm minimum
		• 802.11g: +17.5dBm minimum
		• 802.11a: +18.5dBm minimum
		• 802.11n HT20(2.4GHz): +15.5dBm minimum
		• 802.11n HT40(2.4GHz): +14.5dBm minimum



Technical Specifications

Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Operating Voltage	3.3v +/- 9%	149 to 1509 5 (109 to 709 5)
Weight	1. Type 2230: 2.8g 2. Type 126: 1.3g	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Form Factor	support WLAN MIMO PCI-Express M.2 Mini	
Antenna type	High efficiency anten enclosure	na with spatial diversity, mounted in the display
-	802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ax, MCS11(HT40): -59dBm maximum 802.11ax, MCS11(VHT160): -58.5dBm maximum	
Receiver Sensitivity ³	802.11 compliant power saving mode 802.11b, 1Mbps: -93.5dBm maximum	
Power Management		compliant power management
Power Consumption	•Transmit mode 2.0 •Receive mode 1.6 W •Idle mode (PSP) 180 •Idle mode 50 mW (V •Connected Standby) mW (WLAN Associated) /LAN unassociated)
	• 802.11n HT40(5GH • 802.11ac VHT80(50 • 802.11ac VHT160(5 • 802.11ac VHT160(5	z): +15.5dBm minimum z): +14.5dBm minimum GHz): +11.5dBm minimum GGHz): +11.5dBm minimum GHz): +10dBm minimum GHz): +10dBm minimum

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0/5.1 Compliant

Frequency Band

2402 to 2480 MHz

(III)

Technical Specifications

Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)		
Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary.		
Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels		
Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.		
Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW		
Microsoft Windows Bluetooth Software		
Microsoft Windows ACPI, and USB Bus Support		
FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark		
BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)		

Wireless access point and Internet service is required. Availability of public wireless access point is limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices
 The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
 Check latest software/driver release for updates on supported security features.



4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Intel® XMM™ 7360 LTE- Advanced CAT9⁵	Technology/Operating bands	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66). TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz
	Wireless protocol standards	3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to 450Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
	GPS	Standalone, A-GPS (MS-A, MS-B)
	GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz
	Maximum data rates	LTE: 450 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
	Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm
	Maximum power consumption	LTE: 1,200 mA; 900 mA (average) HSPA+: 1,100 mA; 800 mA (average)
	Form Factor	М.2, 3042-S3 Кеу В
	Weight	5.8 g
	Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm

5. Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Technical Specifications

Intel [®] XMM 7262 LTE- Advanced Cat 6 ⁶	Technology/Operating bands	FDD LTE: 2100 (Band 1), 1800 (Band 3), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 800 (Band 20), 700 (Band 28), HSPA+: 2100 (Band 1), 850 (Band 5), 900 (Band 8)
	Wireless protocol standards	3GPP Release 11 LTE Specification CAT.6, DL 40MHz BW throughput up to 300Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
	GPS	Standalone, A-GPS (MS-A, MS-B and XTRA)
	GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz
	Maximum data rates	LTE: 300 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) UMT: 384 kbps (Download), 384 kbps (Upload)
	Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm
	Maximum power consumption	LTE: 1,200 mA; 900 mA (average) HSPA+: 1,100 mA; 800 mA (average)
	Form Factor	М.2, 3042-S3 Кеу В
	Weight	6 g
	Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm

6. Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Intel® XMM™ 7560 LTE- Advanced Pro CAT16	Technology/Operating bands	 FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 14 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1900 (Band 25), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66). TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41), 3500 (Band 42), 5200 (Band 46 RX only) HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MH
	Wireless protocol standards	3GPP Release 12 LTE Specification DL-CAT.16, DL 100MHz BW throughput up to 978Mbps; UL-CAT.13 40MHz throughput up to 150Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
	GPS	Standalone, A-GPS (MS-B and LTO)
	GPS bands	GPS 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 ± 2.046 MHz



Maximum data rates	LTE: 978 Mbps (Download), 150 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
Maximum output power	LTE: 23 dBm in all bands except B41 LTE B41 HPUE: 26dBm HSPA+: 23.5 dBm
Maximum power consumption	LTE: 1,200 mA; 900 mA (average) HSPA+: 1,100 mA; 800 mA (average)
Form Factor	M.2, 3042-S3 Key B
Weight	6 g
Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm

Near Field Communications Controller	Dimensions (L x W x H)	Module 17 mm by 10 mm by 2.0 mm
	Chipset	NPC300
	System interface	12C
	NFC RF standards	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2
	NFC Forum Support	Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2
	Reader (PCD-VCD) Mode(1)	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards
	Card Emulation (PICC- VICC) Mode(1)	ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa
	Frequency	13.56 MHz
	NFC Modes Supported	Reader/Writer, Peer-to-Peer
	Raw RF Data Rates	106, 212, 424, 848 kbps
	Operating temperature	-25 C to 80°C
	Storage temperature	-20°C to 125°C

	Humidity	10-90% operating 5-95% non-operating
	Supply Operating voltage	
	I/O Voltage	1.8V or 3.3V
Power Consumption	Polling	710.93 mW
(Booster enable, VBAT= 3.3V, VCC_BOOST = 5V)	Detected Test Tag Type 1	152.09 mW
3.3V, VCC_BOU31 - 5V)	Detected Test Tag Type 2	341.26 mW
	Detected Test Tag Type 3	383.76 mW
	Detected Test Tag Type 4	312.26 mW
	Antenna	Antenna connector, 0.3mm pitch, 7 connector FPC. Antenna matching is external to module.
Intel [®] i219LM	Connector	RJ-45
10/100/1000 Integrated NIC	System Interface	PCI (Intel proprietary) + SMBus
integrateu Mic	Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
	Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K
	Power consumption	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
	Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	Management Interface	Auto MDI/MDIX Crossover cable detection
	IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)



	PXE 2.1 Remote Boot
	Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x,
	clause 30))
	Comprehensive diagnostic and configuration software suite
	Virtual Cable Doctor for Ethernet cable status
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel® i219v	Connector	RJ-45
10/100/1000 Integrated NIC	System Interface	PCI (Intel proprietary) + SMBus
NIC	Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21- 30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
	Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K
	Power consumption	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
	Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	Management Interface	Auto MDI/MDIX Crossover cable detection
	IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status

POWER

AC Adapter 45 Watt nPFC Wall Mount USB type C Straight 1.8m C6NS	Dimensions Weight Input	62.0 x 62.0 x 28.5mm unit: 220g +/- 10g Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100%
	mput	input Linciency	load condition with 115Vac/230Vac Spec: 5V: 81.5% 9V: 86.7% 10V: 87.5% 12V: 87.8% 20V: 87.8%
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.4 A at 90 Vac
	Output	Output power	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec
		DC output	5V: 81.5%
		Hold-up time	9V: 86.7%
		Output current limit	10V: 87.5%
		Connector	Non-Standard C6
	Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20°to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	Worldwide safety standard SELV; Agency approvals - (FCC Class B, CISPR22 Class	with LVD and EMC directives ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, B, CCC, NOM-1 NYCE. s at 25°C ambient condition.



Technical Specificati	ons
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AC Adapter 45 Watt	Dimensions	95.0 x 40.0 x 26.5 mm		
Smart nPFC Standard	Weight	unit: 200 g +/- 10 g		
Barrel 4.5mm Right Angle 1.8m	Input	Input Efficiency	87.74 % at 115 Vac and 88.4 % at 230Vac	
		Input frequency range	47 ~ 63 Hz	
		Input AC current	Max. 1.4 A at 90 Vac	
	Output	Output power	45 W	
		DC output	19.5 V	
		Hold-up time	5ms at 115 Vac input	
		Output current limit	<8.0A	
	Connector	C6		
	Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)	
		Non-operating (storage) temperature	-4°F to 185°F (-20°to 85°C)	
		Altitude	0 to 16,400 ft (0 to 5000m)	
		Humidity	20% to 95%	
		Storage Humidity	10% to 95%	
	Safety Certifications	Worldwide safety standard SELV; Agency approvals - C FCC Class B, CISPR22 Class	vith LVD and EMC directives Is - IEC60950, EN60950, UL60950, Class1, UL-US, NORDICS, DENAN, EN55022 Class B, B, CCC, NOM-1 NYCE. s at 25°C ambient condition.	
AC Adapter 45 Watt	Dimensions	95.0 x 40.0 x 26.5 mm		
Smart nPFC Standard Barrel 4.5mm Right Angle 1.8m 2 prong	Weight	unit: 200 g +/- 10 g		
	Input	Input Efficiency	87.74 % at 115 Vac and 88.4 % at 230Vac	
		Input frequency range	47 ~ 63 Hz	
		Input AC current	Max. 1.4 A at 90 Vac	
	Output	Output power	45 W	
		DC output	19.5 V	
		Hold-up time	5 msec at 115 VAC input	
		Output current limit	<8.0A	
	Connector	C8		
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)	
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)	
		Altitude	0 to 16,400 ft (0 to 5000m)	
		Humidity	20% to 95%	
		Storage Humidity	10% to 95%	
	Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Cla FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.		
AC Adapter 65 Watt nPFC	Dimensions	74 x 74 x 28.5 mm		
USB type C Straight 1.8 m	Weight	unit: 245 g +/- 10 g		
C6NS	Input	Input Efficiency	81.5% min at 115 Vac/ 230Vac @ 5V/3A	



HP EliteBook 840 G6 Notebook PC

Technical Specifications

			86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A
		Input frequency range	47 ~ 63 Hz
	0	Input AC current	1.7 A at 90 VAC and maximum load
	Output	Output power	65 W
		DC output	5V/9V/10V/12V/15V/20V
		Hold-up time Output current limit	5ms at 115 Vac input <8.0A
	Connector	Non-Standard C6	0.011
	Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)
	-	Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	5% to 95%
		Storage Humidity	5% to 95%
	Safety Certifications	Worldwide safety standard SELV; Agency approvals - (FCC Class B, CISPR22 Class	vith LVD and EMC directives Is - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, B, CCC, NOM-1 NYCE. s at 25°C ambient condition.
AC Adapter 65 Watt	Dimensions	102 x 55 x 30 mm	
Smart nPFC EM Barrel	Weight	unit: 250 g +/- 10 g	
4.5 mm New EM	Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.7 A at 90 Vac
	Output	Output power	65 W
		DC output	19.5 V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<11.0 A
	Connector	C6	
	Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)
		Non-operating (storage) temperature	
		Altitude	0 to 5,000 m
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	Safety CertificationsCE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, C SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.		ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, B, CCC, NOM-1 NYCE.



AC Adapter 65 Watt Smart nPFC Standard Barrel 4.5 mm Right Angle 1.8 m	Dimensions Weight Input Output	90.0 x 51 x 28.5 mm unit: 230 g +/- 10 g Input Efficiency Input frequency range Input AC current Output power DC output Hold-up time Output current limit	88.0 % at 115 Vac and 89.0 % at 230Vac 47 ~ 63 Hz Max. 1.7 A at 90 Vac 65 W 19.5 V 5ms at 115 Vac input <11.0 A
	Connector	C6	<11.0A
	Environmental Design	4.5mm Barrel Type	
		Operating temperature	32°F to 95°F (0°to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20°to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000 m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	Safety Certifications	Worldwide safety standar SELV; Agency approvals – FCC Class B, CISPR22 Class	with LVD and EMC directives ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, 5 B, CCC, NOM-1 NYCE. 5 at 25°C ambient condition.
Battery SS 3 Cell 50 WHr Long Life -PL	Dimensions	L 278.7 mm x W 76.3 mm	x H 7.1 mm
-	Weight	193 +/- 10 g	
	Cells/Type	3cell Lithium-Ion Polymer	cell / P604883A1
	Energy	Voltage	11.55V
		Amp-hour capacity	4.113Ah/ 4.330Ah
	_	Watt-hour capacity	50Wh
	Temperature	Operating (Charging)	0° to 50° C
		Operating (Discharging)	-10° to 60° C
	Warranty	based on system offering	
	Optional Travel Battery Available	No	

COUNTRY OF ORIGIN

China



Options and Accessories (sold separately and availability may vary by country)

CasesHP Essential Top Load Case (up to 15.6")H2W17AA#HP Slim Ultrabook Top LoadF3W15AA#	
HP Slim Ultrabook Top Load F3W15AA#	xxx
HP Basic/Essential Backpack H1D24AA#	xxx
HP Exec Midnight 15.6" Backpack 1KM16AA#	ххх
Docking HP UltraSlim Docking Station D9Y32AA#	xxx
HP UltraSlim Docking Station TAA US E5C22AV#A	ΒA
HP Thunderbolt Dock 120W G2 2UK37	'AA
HP Thunderbolt Dock 120W G2 TAA 2UK37	'AA
HP Thunderbolt Dock 230W G2 2UK38	BAA
HP TB Dock Audio Module 3AQ21	AA
HP TB Dock 120W G2 cable 3XB94	AA
HP TB Dock G2 combo cable 3XB96	5AA
HP USB-C Universal Dock 1MK33AA#	ххх
HP Elite 90W Thunderbolt 3 Dock 1DT93AA#	xxx
HP USB-C Dock G4 3FF69AA#	xxx
HP USB-C Mini Dock 1PM64AA#	ххх
HP USB-C Travel Dock T0K29AA#	ххх
HP USB Travel Dock TOK30AA#	ххх
HP USB-C Universal Dock w/4.5mm Adapter 2UF95	5AA
HP USB-C Universal Dock w/4.5mm Adapter - non-flash 3DV65 version	5AA
HP USB-C Dock G5 5TW10AA#	xxx
HP USB-C/A Universal Dock G2 5TW13AA#	ххх
HP Adjustable Dual Display Stand AW664AA#	ххх
HP Display and Notebook Stand II E8G00AA#	ххх
HP TB Dock G2 w/ Combo Cable 3TR87	'AA
HP TB Dock 120W G2 w/ Audio 3YE87	'AA
Input/Output HP Slim Wireless Keyboard and Mouse T6L04AA#	ххх
HP Slim USB Keyboard and Mouse T6T83AA#	xxx
HP Wireless (Link-5) Keyboard T6U20AA#	ххх
HP USB Essential Keyboard and Mouse H6L29AA#	xxx
HP Conferencing Keyboard K8P74AA#	ххх
HP USB Collaboration Keyboard Z9N38AA#	ххх
HP Wireless Collaboration Keyboard Z9N39AA#	ххх
HP Comfort Grip Wireless Mouse H2L63AA#	ххх
HP X4000b Bluetooth Mouse H3T50AA#	xxx
HP 3-Button USB Laser Mouse H4B81AA#	xxx
HP USB Travel Mouse G1K28AA#	ххх
HP Ultra Mobile Wireless Mouse H6F25AA#	ххх
HP Slim Bluetooth Mouse to AMO F3J92AA#	ххх
HP Wireless Premium Mouse 1JR31AA#	XXX



Options and Accessories (sold separately and availability may vary by country)

	HP USB Premium Mouse	1JR32AA#xxx
	HP Essential USB Mouse	2TX37AA#xxx
	HP Elite Presenter Mouse	2CE30AA#xxx
	HP USB-C to USB 3.0 Adapter	N2Z63AAA#xxx
	HP USB-C to USB-A Hub	Z6A00AA#xxx
	HP USB-C to DP	N9K78AA#xxx
	HP USB-C to VGA	N9K76AA#xxx
	HP HDMI to DVI	F5A28AA#xxx
	HP HDMI to VGA	H4F02AA#xxx
	HP USB-C to HDMI 2.0 Adapter	1WC36AA#xxx
Power	HP 65W Slim AC Adapter	H6Y82AA#xxx
	HP 90W Slim AC Adapter	H6Y83AA#xxx
	HP 90W Slim Combo AC Adapter w/ USB	H6Y84AA#xxx
	HP 45W Smart AC Adapter	H6Y88AA#xxx
	HP 65W Smart AC Adapter	H6Y89AA#xxx
	HP 90W Smart AC Adapter	H6Y90AA#xxx
	HP 45W 2-prong 4.5 mm DC jack AC Adapter	L6F60AA#ABJ
	HP 45W USB-C Power Adapter	1HE07AA#xxx
	HP 65W USB-C Power Adapter	1HE08AA#xxx
	65W USB-C Slim Power Adapter	3PN48AA
	HP Notebook Power Bank	N9F71AA#xxx
	HP USB-C Notebook Power Bank	1TZ86AA#xxx
	HP 45W USB-C Power Adapter	1HE07AA#xxx
	HP 65W USB-C Power Adapter	1HE08AA#xxx
Storage	HP USB External DVDRW Drive	F2B56AA#xxx
	HP 256GB M2 PCIe NVME SSD TLC 2280	1FU87AA#xxx
	HP 512GB M2 PCIe NVME SSD TLC 2280	1FU88AA#xxx
Security	HP Docking Station Cable Lock	AU656AA#xxx
	HP Essential Combination Lock	T0Y16AA#xxx
	HP Combination Lock	T0Y15AA#xxx
	HP Keyed Cable lock	T0Y14AA#xxx
	HP Keyed Cable Lock 10mm	T1A62AA#xxx
	HP Dual Head Keyed Cable Lock	T1A64AA#xxx



Options and Accessories (sold separately and availability may vary by country)

UCC	HP Stereo 3.5mm Headset HP Stereo USB Headset HP UC Wireless Mono Headset HP UC Wireless Duo Headset	T1A66AA#xxx T1A67AA#xxx W3K08AA#xxx W3K09AA#xxx
Displays	HP EliteDisplay E243d 23.8-inch Docking Monitor HP EliteDisplay E243 23.8-inch Monitor HP EliteDisplay E273q 27-inch Monitor	1TJ76AA 1FH47AA 1FH52AA



Summary of Changes Change Log

Date of change:	Version History:		Description of change:
May 23, 2019	V1 to V2	Added	Environmental Section
May 30, 2019	V2 to V3	Updated	Lock Slot

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